AND MUTLI-LIQUID-PRECURSOR VAPORIZATION IN SEMICONDUCTOR THIN FILM DEPOSITION

ABSTRACT OF THE DISCLOSURE

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A vaporization system for thin film formation and for introducing vapors into a deposition chamber for depositing films onto a semi-conductor surface has vaporization chamber that is selectively provided with at least two different, separate, precursor liquids carried in a gas stream that may be single carrier gas, or a selected one of a plurality of carrier gasses. When the liquids being introduced are likely to be subject to thermal decomposition from contact with high temperature surfaces, an atomizer is used at the inlet of the vaporization chamber to provide an aerosol to the vaporization chamber from one or more individual sources οf liquid combined with one orindividual carrier qasses for simultaneous sequential introduction into the vaporization chamber. The vaporization chamber may be designed to complete vaporization by incorporating a insure recirculating gas flow through heated passageways before the vaporized gas/vapor mixture exits vaporization chamber.